

SaTC-EDU: Collaborative: Cybersecurity Education for Additive Manufacturing



NYU

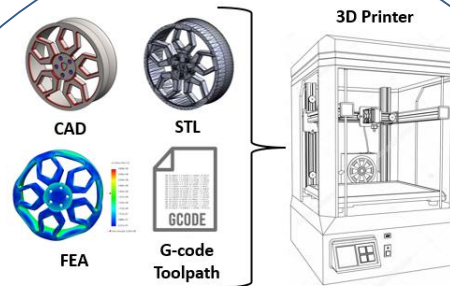
Center for
Cybersecurity

Challenge:

- Develop resources on the topic of manufacturing cybersecurity for students and professionals
- Provide hands on experience with hackathon challenges

Solution:

- Hack3D – student competition on manufacturing security
- Webinars – gathering of manufacturing cybersecurity community



Additive Manufacturing process involves digital design files to create printed part

Attack Goals	Attack Methods	Attack Targets
<ul style="list-style-type: none">• Piracy• Sabotage• Counterfeiting• Reverse engineering	<ul style="list-style-type: none">• Denial of Service• Tamper Data• IP Theft• Side Channel	<ul style="list-style-type: none">• CAD designs• AM Machine• Sensors• Controllers• Data stream

Hidden threats in the AM digital process chain

Goal: Train engineers to confront cybersecurity challenges during product design, development, and manufacturing

Scientific Impact:

- Educate a new group of workforce with multidisciplinary knowledge
- Build a library of educational resources for both students and professionals

Broader Impact and Broader Participation:

- Bridge gap in engineering and cybersecurity disciplines by developing a comprehensive education and training initiative
- Worked with over 1000 people in multiple events

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